

SCHROFF INTERSCALE C FOR EMBEDDEDNUC™

CONDUCTION COOLED CASE SOLUTION COMPLIANT WITH EMBEDDEDNUC™ STANDARD



Schroff Interscale C cases, leveraging the same proven design as Interscale M cases, feature an interlocking tabbed construction that provides integrated EMC protection and secures with only two screws.

Interscale C cases have integrated heat sinks and are compatible with Schroff's Flexible Heat Conductors (FHC) for industry leading conduction cooling performance.

Available in standard or custom solutions, with support from prototype through production.

TECHNICAL DETAILS AND BENEFITS

Standards based design

- Compliant with the SDT.03 embeddedNUC™ standard <http://www.sget.org/standards.html>
- Cut-outs specific for IES MB95 embeddedNUC™ board (<http://en.ies.de/>)
- Compact size: 44 x 112 x 107 mm (H x W x D)

Flexible platform

- Custom case sizes and heat sink fin heights available, as well as options for different cut-out size and locations, powder coating colors and printing
- Design elements available to create a unique look or corporate branding

Simple to assemble, performance centric design

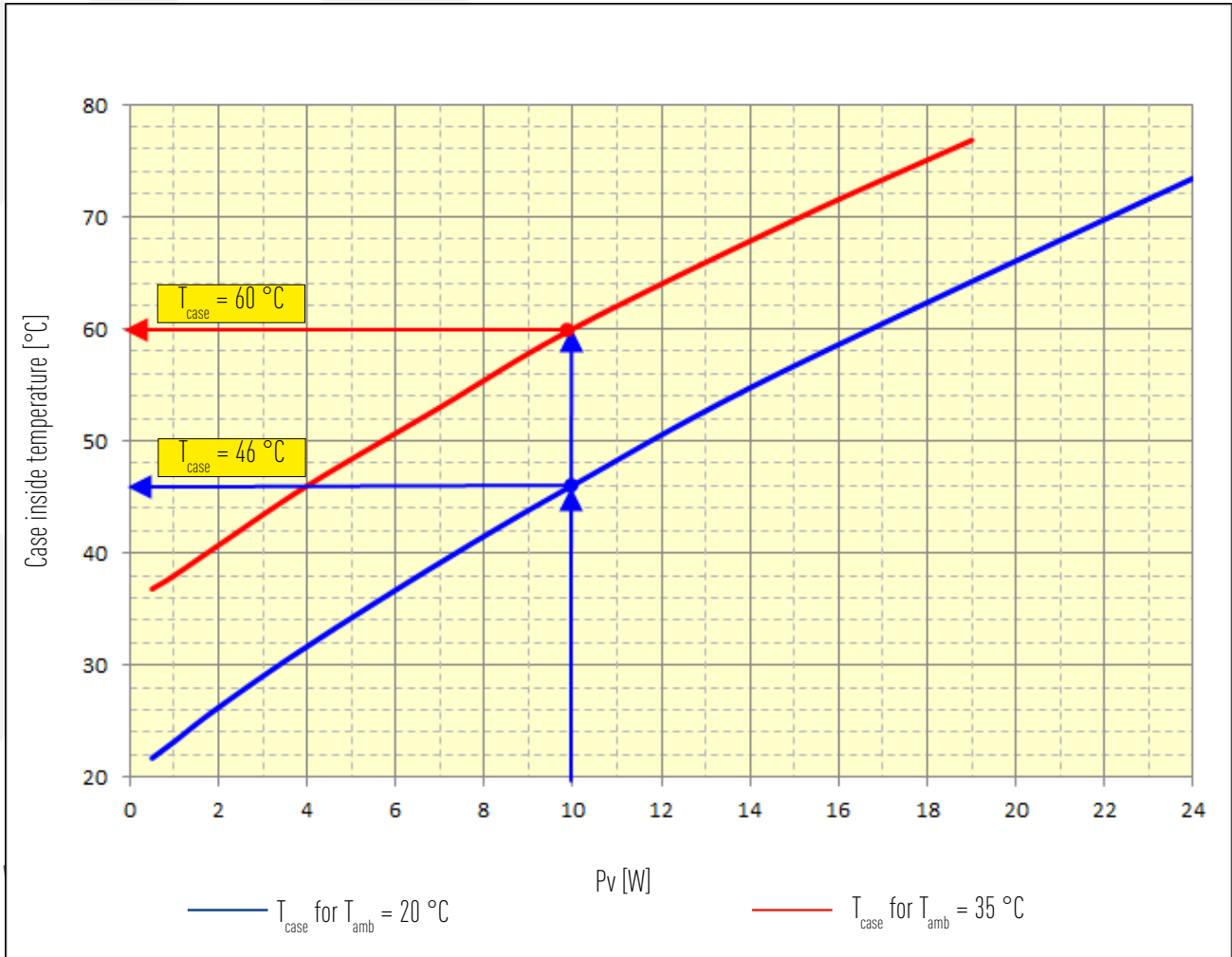
- Ideal for use in industrial applications
- 5 mm heat sink is integrated into the case cover; provided assembled
- Pre-installed M2.5 studs for board mounting
- Modular case consisting of 3 easy to assemble parts requires only two screws
- Innovative design integrated provides EMC protection up to 20 dB at 2 GHz
- Ingress protection up to IP 30

Schroff

CASE INSIDE TEMPERATURE

FHC 20 MM INSIDE INTERSCALE C CASE

Heat transfer coefficient $h = 7 \text{ w}/(\text{m}^2\text{K})$

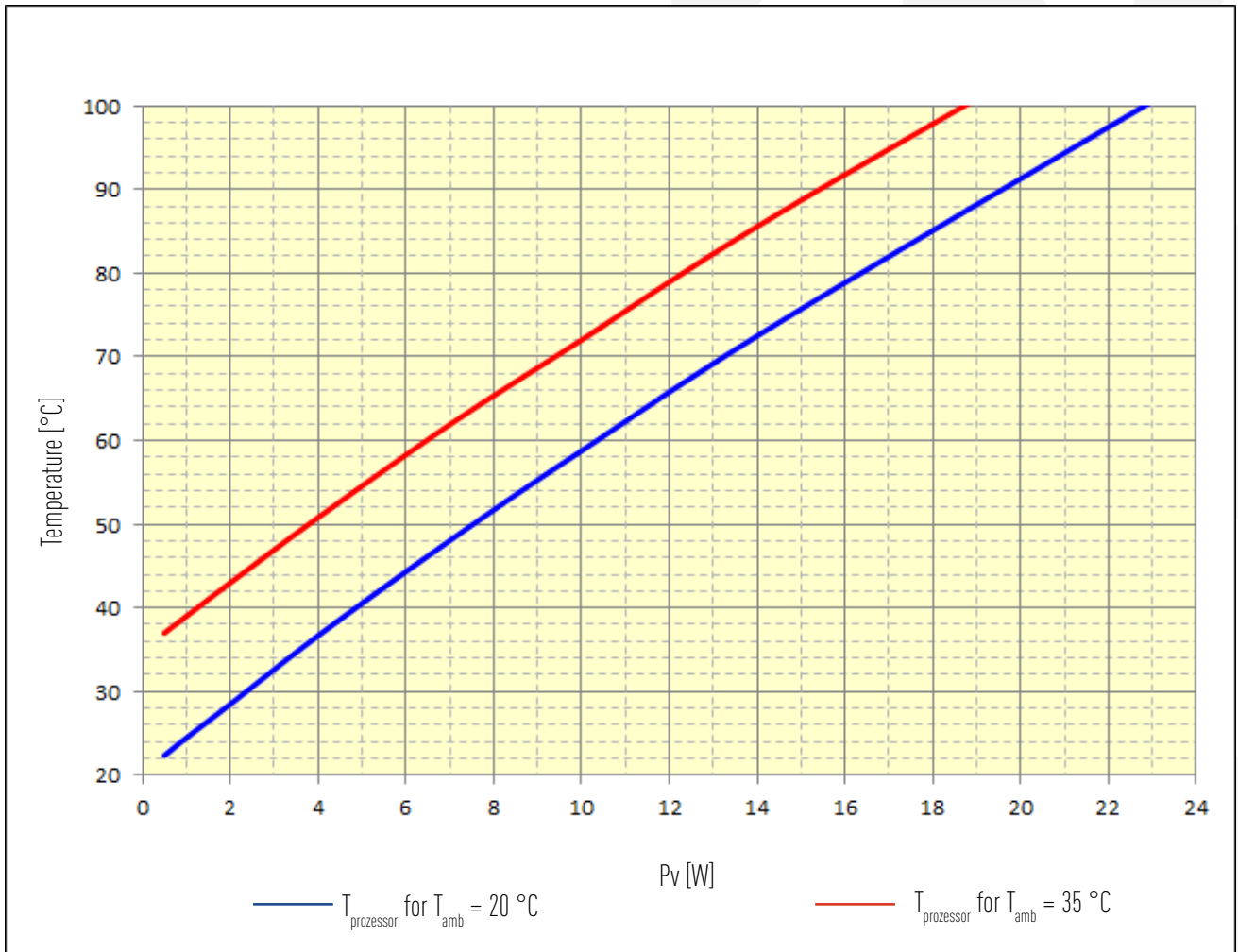


Tested with Mini-ItX Board Core I7 processor 4770.

PROCESSOR SURFACE TEMPERATURE

FHC 20 MM INSIDE INTERSCALE C CASE

Heat transfer coefficient $h = 7 \text{ w}/(\text{m}^2\text{K})$



Tested with Mini-ItX Board Core I7 processor 4770.

SCHROFF INTERSCALE C FOR EMBEDDEDNUC™

Total conduction cooling solution

- Compatible with the Flexible Heat Conductor (FHC) for 10%-20% greater thermal dissipation than traditional conduction cooling
- The integrated springs within the FHC allow the aluminum block to expand and contract vertically thereby eliminating the need for a thermal gap pad
- Interscale C, with the FHC, provide consistent performance over the lifetime of the system
- Complies with the requirements for “top side cooling” per the SDT.03 embeddedNUC™ standard
- Whitepaper, including thermal test procedures and results, available



ORDER INFORMATION

Description	Item no.	
Bundle consists of:	14891-237	
Interscale C for embeddedNUC™	•	
Flexible Heat Conductor (FHC), 20 mm	•	
Rubber feet, adhesive	•	
Assembly tool	•	
Aesthetic design elements, adhesive, 2 pcs. (please order separately)	Blue - RAL 5010	24830-010
	Red - RAL 3027	24830-011
	Silver - RAL 9006	24830-012



EUROPE

Straubenhardt, Germany
Tel: +49.7082.794.0

Betschdorf, France
Tel: +33.3.88.90.64.90

Warsaw, Poland
Tel: +48.22.209.98.35

Hemel Hempstead, Great Britain
Tel: +44.1442.24.04.71

Skarpnäck, Sweden
Tel: +46.8.683.61.00
Lainate, Italy
Tel: +39.02.932.714.1

NORTH AMERICA

All locations
Tel: +1.800.525.4682

MIDDLE EAST & INDIA

Dubai, United Arab Emirates
Tel: +971.4.37.81.700

Bangalore, India
Tel: +91.80.6715.2001

Istanbul, Turkey
Tel: +90.216.250.7374

ASIA

Shanghai, P.R. China
Tel: +86.21.2412.6943

Qingdao, China
Tel: +86.523.8771.6101

Singapore
Tel: +65.6768.5800

Shin-Yokohama, Japan
Tel: +81.45.476.0271

Langenalber Str. 96-100, D-75334 Straubenhardt

Pentair and schroff are owned by Pentair or its global affiliates. All other trademarks are the property of their respective owners.